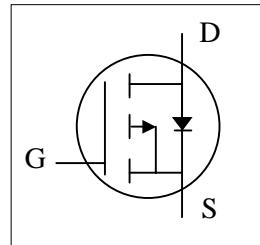




- ▼ Lower On-resistance
- ▼ Simple Drive Requirement
- ▼ Fast Switching Characteristic
- ▼ RoHS Compliant

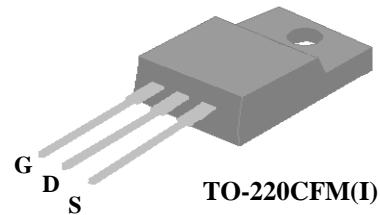


$BV_{DSS}$	-30V
$R_{DS(ON)}$	28mΩ
$I_D$	-30A

## Description

Advanced Power MOSFETs from APEC provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220CFM isolation package is widely preferred for all commercial-industrial through hole applications.



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-30	V
$V_{GS}$	Gate-Source Voltage	+20	V
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	-30	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	-18	A
$I_{DM}$	Pulsed Drain Current <sup>1</sup>	-120	A
$P_D @ T_C = 25^\circ C$	Total Power Dissipation	31.3	W
	Linear Derating Factor	0.25	W/°C
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

## Thermal Data

Symbol	Parameter	Value	Units
$R_{thj-c}$	Maximum Thermal Resistance, Junction-case	4	°C/W
$R_{thj-a}$	Maximum Thermal Resistance, Junction-ambient	65	°C/W



## Electrical Characteristics@ $T_j=25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_{\text{D}}=-250\mu\text{A}$	-30	-	-	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_j$	Breakdown Voltage Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_{\text{D}}=-1\text{mA}$	-	-0.02	-	$\text{V}/^\circ\text{C}$
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=-10\text{V}$ , $I_{\text{D}}=-18\text{A}$	-	-	28	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}$ , $I_{\text{D}}=-10\text{A}$	-	-	50	$\text{m}\Omega$
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$ , $I_{\text{D}}=-250\mu\text{A}$	-1	-	-3	V
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=-10\text{V}$ , $I_{\text{D}}=-18\text{A}$	-	21	-	S
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=-30\text{V}$ , $V_{\text{GS}}=0\text{V}$	-	-	-1	$\text{uA}$
	Drain-Source Leakage Current ( $T_j=125^\circ\text{C}$ )	$V_{\text{DS}}=-24\text{V}$ , $V_{\text{GS}}=0\text{V}$	-	-	-250	$\text{uA}$
$I_{\text{GSS}}$	Gate-Source Leakage	$V_{\text{GS}}=+20\text{V}$ , $V_{\text{DS}}=0\text{V}$	-	-	+100	nA
$Q_g$	Total Gate Charge <sup>2</sup>	$I_{\text{D}}=-18\text{A}$	-	15	24	nC
$Q_{\text{gs}}$	Gate-Source Charge	$V_{\text{DS}}=-25\text{V}$	-	3	-	nC
$Q_{\text{gd}}$	Gate-Drain ("Miller") Charge	$V_{\text{GS}}=-4.5\text{V}$	-	10	-	nC
$t_{\text{d}(\text{on})}$	Turn-on Delay Time <sup>2</sup>	$V_{\text{DS}}=-15\text{V}$	-	10	-	ns
$t_r$	Rise Time	$I_{\text{D}}=-18\text{A}$	-	48	-	ns
$t_{\text{d}(\text{off})}$	Turn-off Delay Time	$R_{\text{G}}=3.3\Omega$ , $V_{\text{GS}}=-10\text{V}$	-	31	-	ns
$t_f$	Fall Time	$R_{\text{D}}=0.8\Omega$	-	66	-	ns
$C_{\text{iss}}$	Input Capacitance	$V_{\text{GS}}=0\text{V}$	-	910	1460	pF
$C_{\text{oss}}$	Output Capacitance	$V_{\text{DS}}=-25\text{V}$	-	300	-	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance	f=1.0MHz	-	210	-	pF
$R_g$	Gate Resistance	f=1.0MHz	-	11	17	$\Omega$

## Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_{\text{SD}}$	Forward On Voltage <sup>2</sup>	$I_{\text{S}}=-18\text{A}$ , $V_{\text{GS}}=0\text{V}$	-	-	-1.3	V
$t_{\text{rr}}$	Reverse Recovery Time <sup>2</sup>	$I_{\text{S}}=-18\text{A}$ , $V_{\text{GS}}=0\text{V}$ ,	-	30	-	ns
$Q_{\text{rr}}$	Reverse Recovery Charge	$dI/dt=-100\text{A}/\mu\text{s}$	-	25	-	nC

## Notes:

1.Pulse width limited by Max. junction temperature.

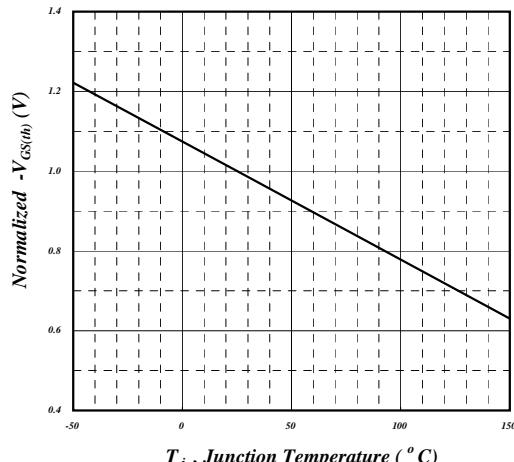
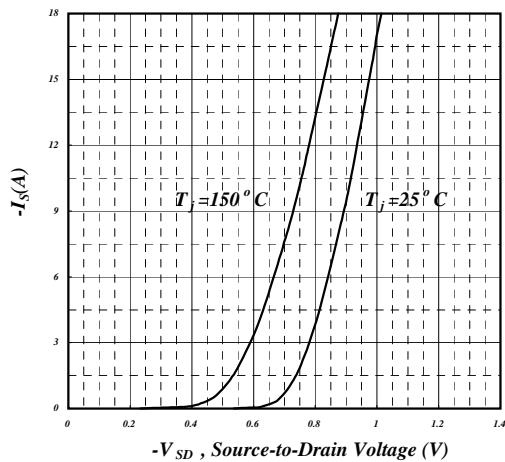
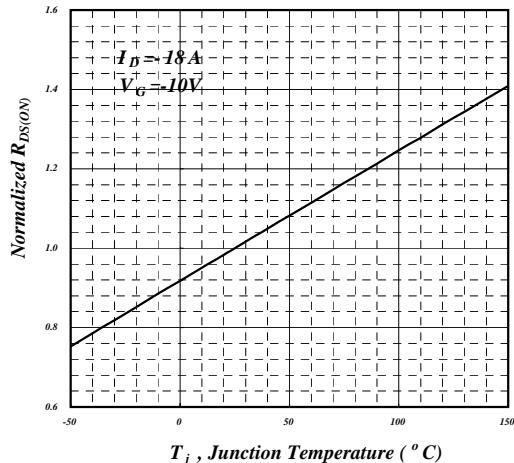
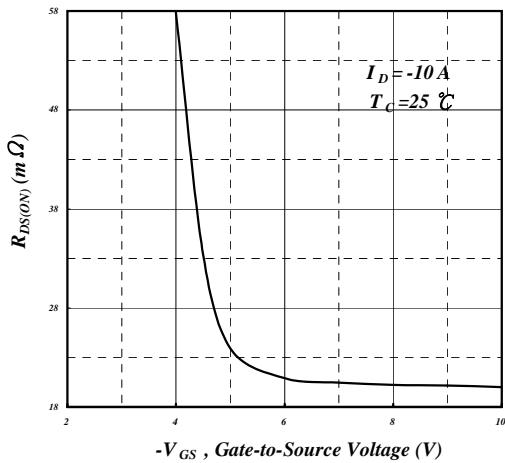
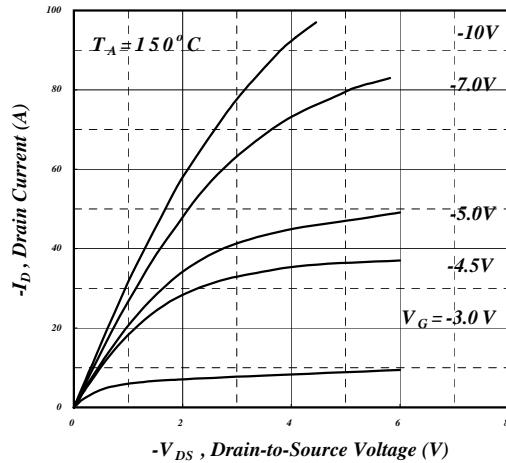
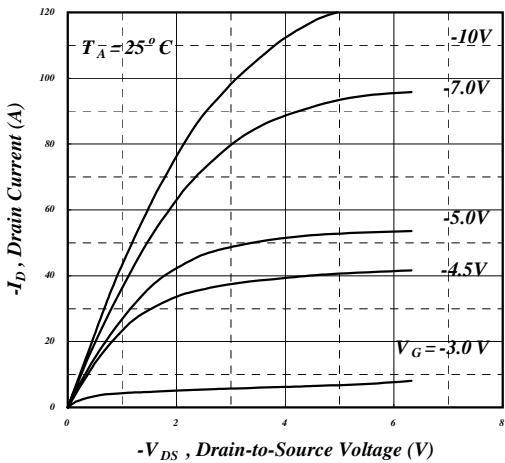
2.Pulse test

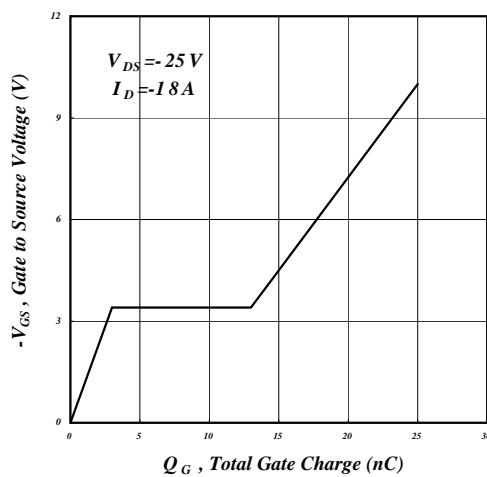
THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

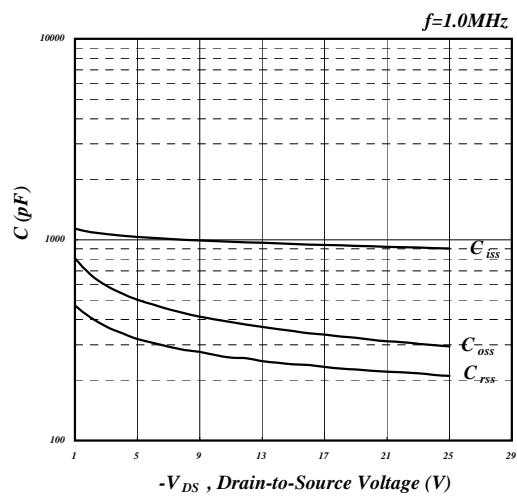
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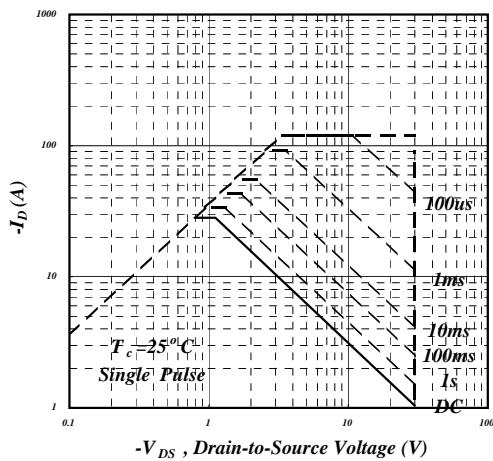




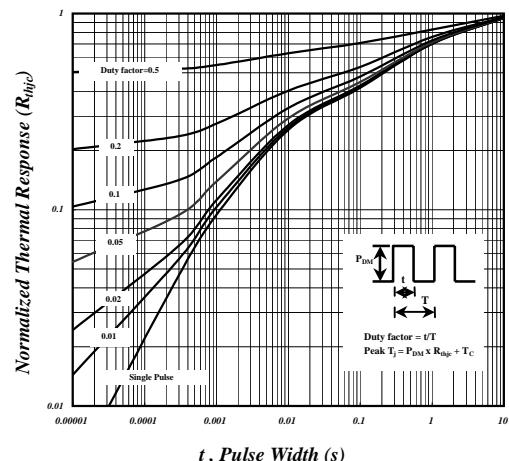
**Fig 7. Gate Charge Characteristics**



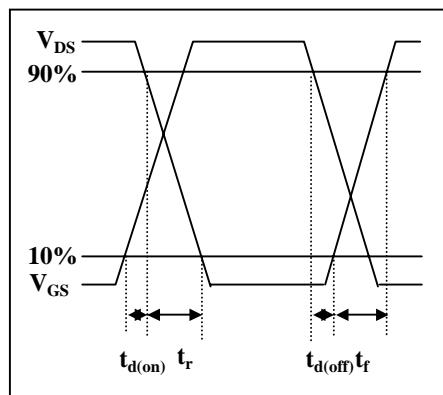
**Fig 8. Typical Capacitance Characteristics**



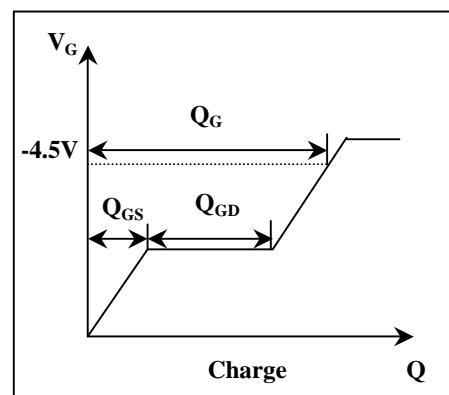
**Fig 9. Maximum Safe Operating Area**



**Fig 10. Effective Transient Thermal Impedance**



**Fig 11. Switching Time Waveform**

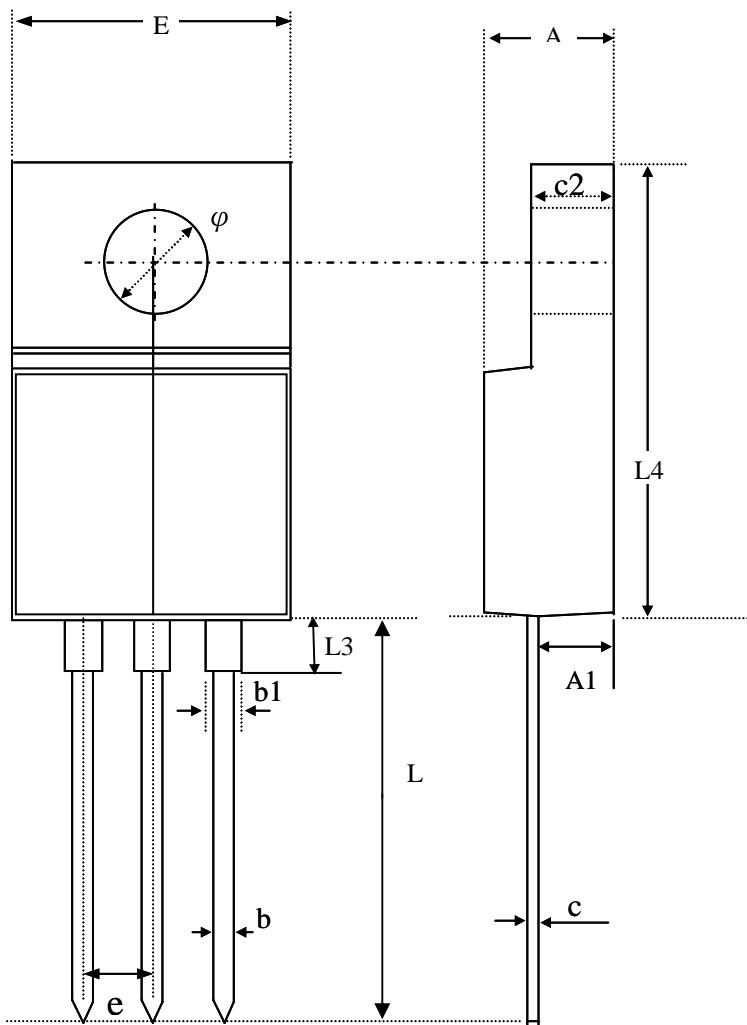


**Fig 12. Gate Charge Waveform**



ADVANCED POWER ELECTRONICS CORP.

## Package Outline : TO-220CFM



SYMBOLS	Millimeters		
	MIN	NOM	MAX
A	4.30	4.70	4.90
A1	2.30	2.65	3.00
b	0.50	0.70	0.90
b1	0.95	1.20	1.50
c	0.45	0.65	0.80
c2	2.30	2.60	2.90
E	9.70	10.00	10.40
L	12.00	---	15.00
L3	2.91	3.41	3.91
L4	14.70	15.40	16.10
φ	----	3.20	----
e	----	2.54	----

1. All Dimensions Are in Millimeters.

2. Dimension Does Not Include Mold Protrusions.

## Part Marking Information & Packing : TO-220CFM

